



Recommended PCB Layout (Top View)

P/N	Post Location	PCB Layout	RAM	Voltage
KDM168X-5.0DR1TN	B, C, D	B, C, D	DRAM	5.0V
KDM168X-3.3DR1TN	B, C, D	B, C, D	DRAM	3.3V
KDM168X-5.0DR2TN	A, D	A, D	DRAM	5.0V
KDM168X-3.3DR2TN	A, D	A, D	DRAM	3.3V
KDM168X-5.0DR3TN	B, C	B, C	DRAM	5.0V
KDM168X-3.3DR4TN	A, C, D	A, C, D	DRAM	3.3V
KDM168X-5.0SD4TN	A, C, D	A, C, D	SDRAM	5.0V
KDM168X-3.3SD4TN	A, C, D	A, C, D	SDRAM	3.3V
KDM168X-5.0UN4TN	A, C, D	A, C, D	Unbuffered DRAM	5.0V
KDM168X-3.3UN4TN	A, C, D	A, C, D	Unbuffered DRAM	3.3V
KDM168X-3.3UN1TN	B, C, D	B, C, D	Unbuffered DRAM	3.3V
KDM168X-3.3UN5TN	A, B, C, D	A, B, C, D	Unbuffered DRAM	3.3V

Material and Finish

Body:
 High Temperature Thermoplastic
 with Glass-fiber Reinforcement
 UL 94V-0 Rated,
 Color: Black

Ejector: Brass

Contact Material: Copper Alloy

Contact Plating:
 Gold Plating over Nickel
 on Contact Area,
 Tin Plating on Terminal

Other Plating Options Available,
 Contact Kycon for Details

Electrical Specifications

Insulation Resistance:
 10,000 Megohm

Dielectric Withstanding:
 1000 V AC RMS for 1 Minute

Operating Temperature:
 -55°C to 105°C

RoHS COMPLIANT
 EU Directive 2002/95/EC

Tolerances
X.X ± 0.25
X.XX ± 0.15
Unless Stated Otherwise

REV.	DATE	DESCRIPTION	REV. BY	CHK. BY	DRAWN BY	DATE
A1	06/16/05	New Drawing	H. MA	C. Furumasu	H. MA	06/16/05
A2	03/11/11	Change Contact Material	S. Vien	H. MA	H. MA	
A3	04/18/13	ECO #13-022	D. Gih	P. DalCanto		
A4	08/23/13	ECO #13-062	D. Gih	P. DalCanto		
A5	03/21/14	Remove CSA	W. Cook	H. MA		

KDM168X-xxxxxxx

168 Position Socket for Dual Inline
 Memory Modules, RoHS Compliant

